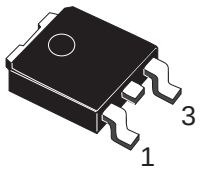
# STD25NF10

## N-CHANNEL 100V - 0.033Ω - 25A DPAK
## LOW GATE CHARGE STripFET™ POWER MOSFET

| TYPE | $V_{DSS}$ | $R_{DS(on)}$ | $I_D$ |
|---|---|---|---|
| STD25NF10 | 100 V | < 0.038 Ω | 25 A |

- TYPICAL $R_{DS}(on)$ = 0.033Ω
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION

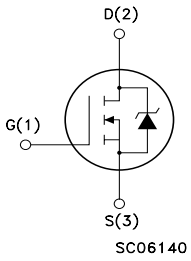



**DPAK**

### DESCRIPTION

This Power Mosfet series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters for Telecom and Computer application. It is also intended for any application with low gate charge drive requirements.

**INTERNAL SCHEMATIC DIAGRAM**




### APPLICATIONS

- HIGH-EFFICIENCY DC-DC CONVERTERS
- UPS AND MOTOR CONTROL

### ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|---|---|---|---|
| $V_{DS}$ | Drain-source Voltage ($V_{GS}$ = 0) | 100 | V |
| $V_{DGR}$ | Drain-gate Voltage ($R_{GS}$ = 20 kΩ) | 100 | V |
| $V_{GS}$ | Gate- source Voltage | ± 20 | V |
| $I_D$ (*) | Drain Current (continuos) at $T_C$ = 25°C | 25 | A |
| $I_D$ | Drain Current (continuos) at $T_C$ = 100°C | 21 | A |
| $I_{DM}$ (●) | Drain Current (pulsed) | 100 | A |
| $P_{TOT}$ | Total Dissipation at $T_C$ = 25°C | 100 | W |
| | Derating Factor | 0.67 | W/°C |
| dv/dt (1) | Peak Diode Recovery voltage slope | 13 | V/ns |
| $E_{AS}$ (2) | Single Pulse Avalanche Energy | 480 | mJ |
| $T_{stg}$ | Storage Temperature | –55 to 175 | °C |
| $T_j$ | Operating Junction Temperature | | |

(●) Pulse width limited by safe operating area
(*) Current Limited by Package

(1) $I_{SD}$ ≤35A, di/dt ≤300A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_j \leq T_{JMAX.}$
(2) Starting $T_j$ = 25°C, $I_D$ = 12.5A, $V_{DD}$ = 50V

## THERMAL DATA

| | | | |
|---|---|---|---|
| Rthj-case | Thermal Resistance Junction-case Max | 1.5 | °C/W |
| Rthj-amb | Thermal Resistance Junction-ambient Max | 100 | °C/W |
| $T_l$ | Maximum Lead Temperature For Soldering Purpose | 300 | °C |

## ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage | $I_D$ = 250 µA, $V_{GS}$ = 0 | 100 | | | V |
| $I_{DSS}$ | Zero Gate Voltage Drain Current ($V_{GS}$ = 0) | $V_{DS}$ = Max Rating | | | 1 | µA |
| | | $V_{DS}$ = Max Rating, $T_C$ = 125 °C | | | 10 | µA |
| $I_{GSS}$ | Gate-body Leakage Current ($V_{DS}$ = 0) | $V_{GS}$ = ±20V | | | ±100 | nA |

ON (1)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$ = $V_{GS}$, $I_D$ = 250µA | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static Drain-source On Resistance | $V_{GS}$ = 10V, $I_D$ = 12.5 A | | 0.033 | 0.038 | Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $g_{fs}$ (1) | Forward Transconductance | $V_{DS}$ = 15 V, $I_D$ = 12.5 A | | 20 | | S |
| $C_{iss}$ | Input Capacitance | $V_{DS}$ = 25V, f = 1 MHz, $V_{GS}$ = 0 | | 1550 | | pF |
| $C_{oss}$ | Output Capacitance | | | 220 | | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | | 95 | | pF |

**ELECTRICAL CHARACTERISTICS** (CONTINUED)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD}$ = 50V, $I_D$ = 12.5 A | | 17 | | ns |
| $t_r$ | Rise Time | $R_G$ = 4.7Ω $V_{GS}$ = 10V (see test circuit, Figure 3) | | 60 | | ns |
| $Q_g$ | Total Gate Charge | $V_{DD}$ = 80V, $I_D$ =25A,$V_{GS}$ = 10V | | 55 | | nC |
| $Q_{gs}$ | Gate-Source Charge | | | 12 | | nC |
| $Q_{gd}$ | Gate-Drain Charge | | | 20 | | nC |

SWITCHING OFF

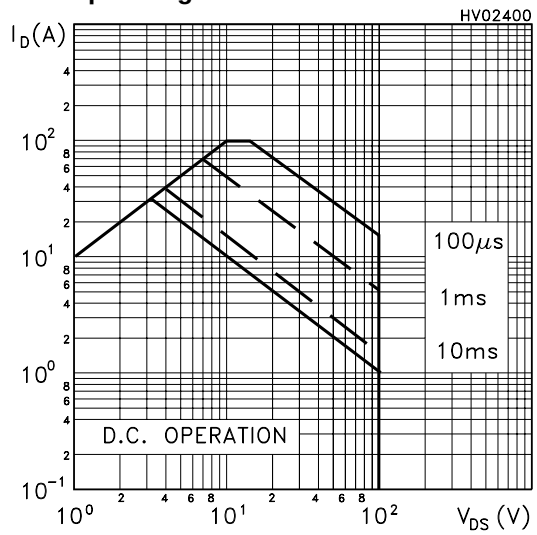
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $t_{d(off)}$ | Turn-off-Delay Time | $V_{DD}$ = 50V, $I_D$ = 12.5 A, | | 60 | | ns |
| $t_f$ | Fall Time | $R_G$ = 4.7Ω, $V_{GS}$ = 10V (see test circuit, Figure 3) | | 15 | | ns |

SOURCE DRAIN DIODE

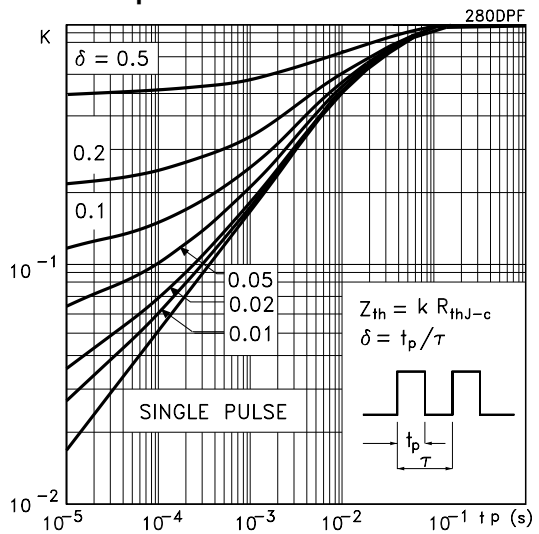
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $I_{SD}$ | Source-drain Current | | | | 25 | A |
| $I_{SDM}$ (1) | Source-drain Current (pulsed) | | | | 100 | A |
| $V_{SD}$ (2) | Forward On Voltage | $I_{SD}$ = 25 A, $V_{GS}$ = 0 | | | 1.5 | V |
| $t_{rr}$ | Reverse Recovery Time | $I_{SD}$ = 25 A, di/dt = 100A/µs, | | 160 | | ns |
| $Q_{rr}$ | Reverse Recovery Charge | $V_{DD}$ = 50V, $T_j$ = 150°C | | | | nC |
| $I_{RRM}$ | Reverse Recovery Current | (see test circuit, Figure 5) | | | | A |

Note: 1. Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
2. Pulse width limited by safe operating area.

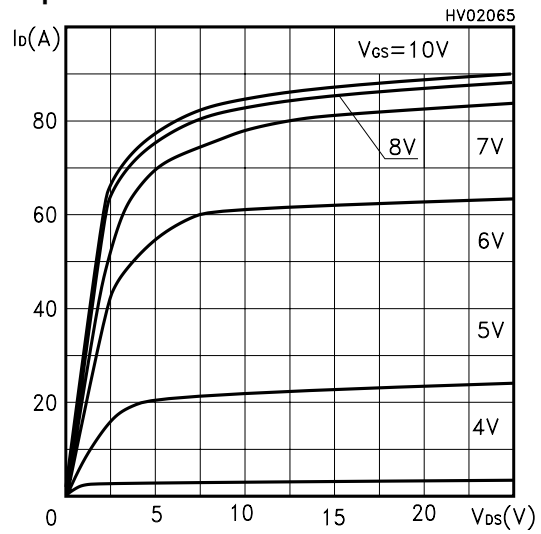
**Safe Operating Area**



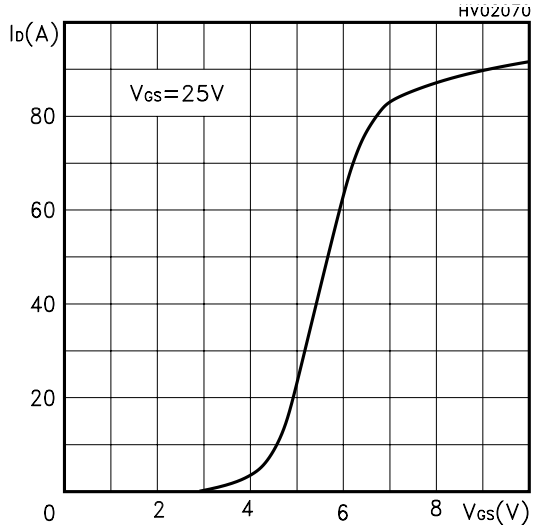

**Thermal Impedence**



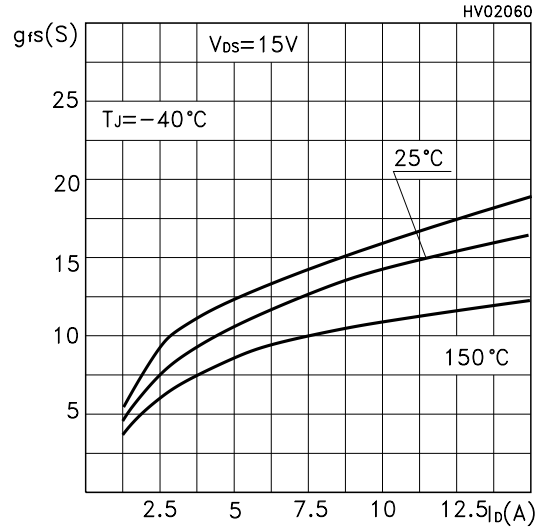
### Output Characteristics



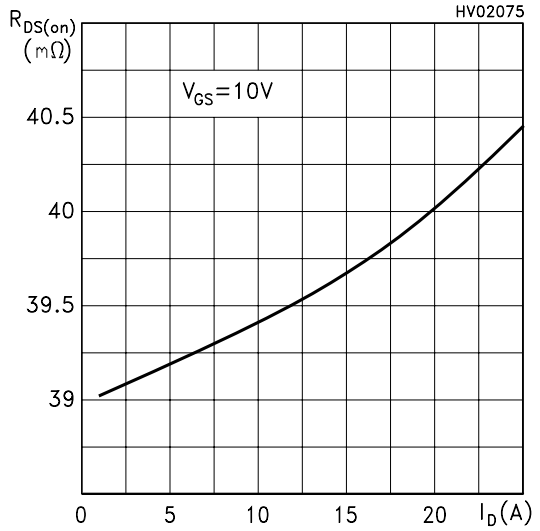

### Transfer Characteristics



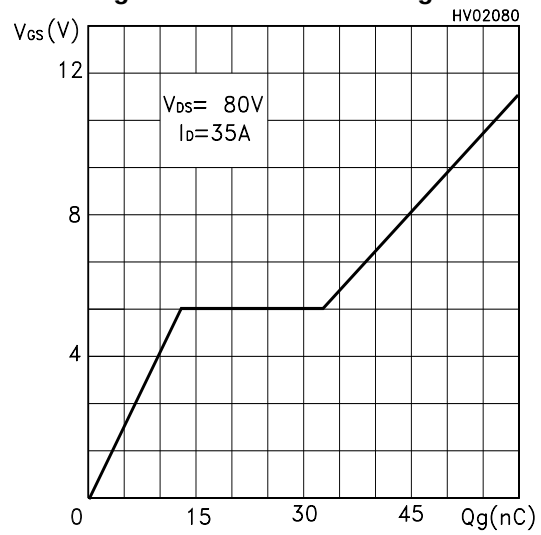

### Transconductance



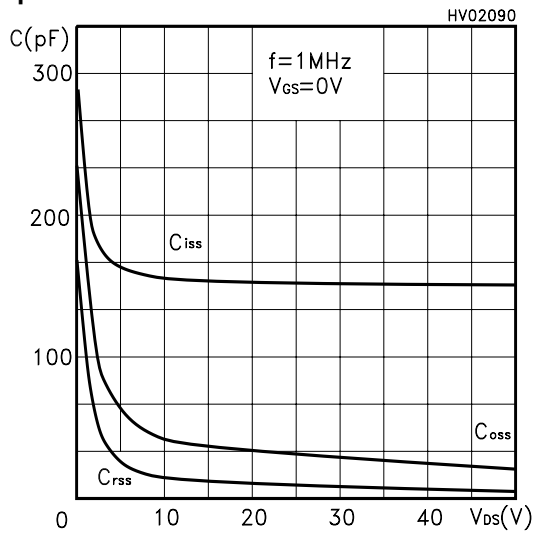

### Static Drain-source On Resistance



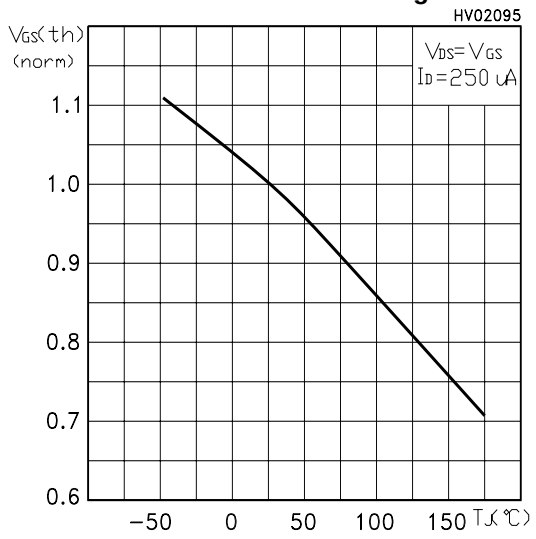

### Gate Charge vs Gate-source Voltage



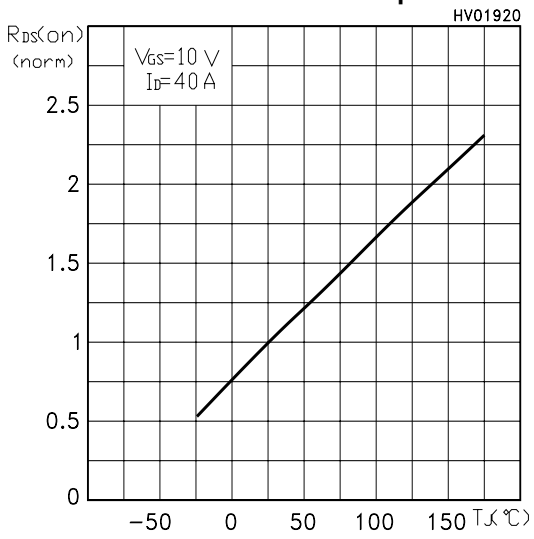

### Capacitance Variations



**Normalized Gate Thereshold Voltage vs Temp.**




**Normalized On Resistance vs Temperature**




**Source-drain Diode Forward Characteristics**

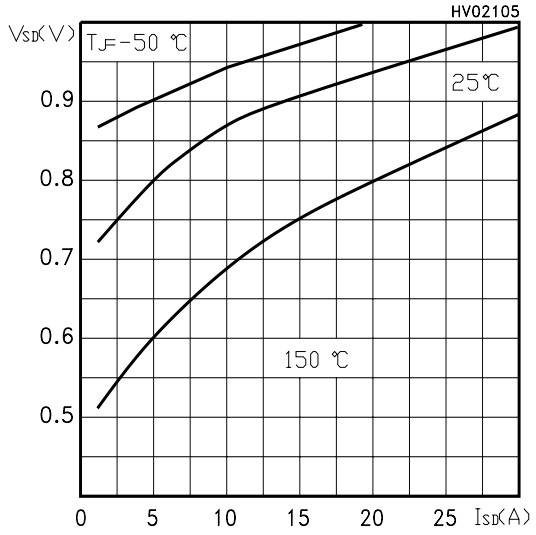


**Fig. 1:** Unclamped Inductive Load Test Circuit

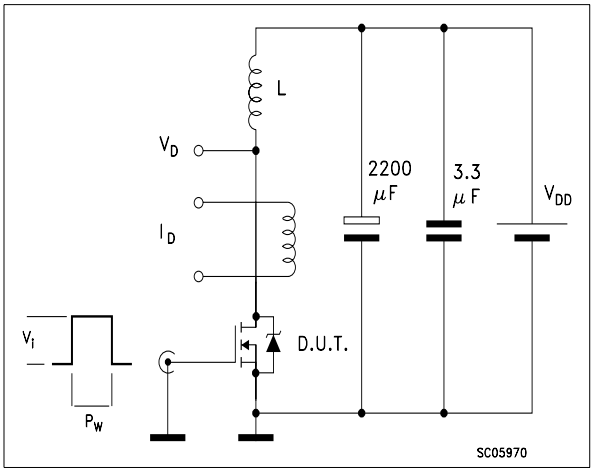



**Fig. 2:** Unclamped Inductive Waveform

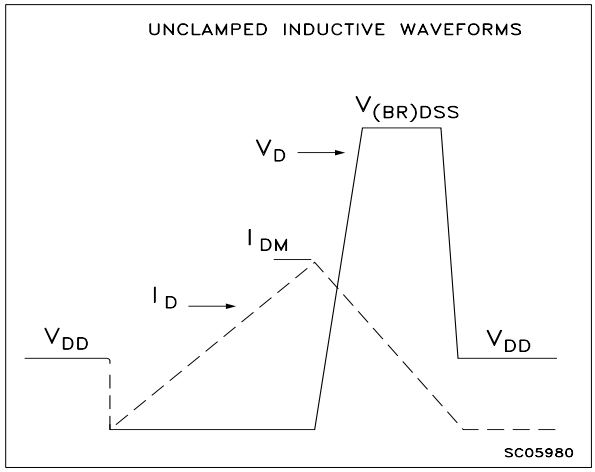



**Fig. 3:** Switching Times Test Circuit For Resistive Load

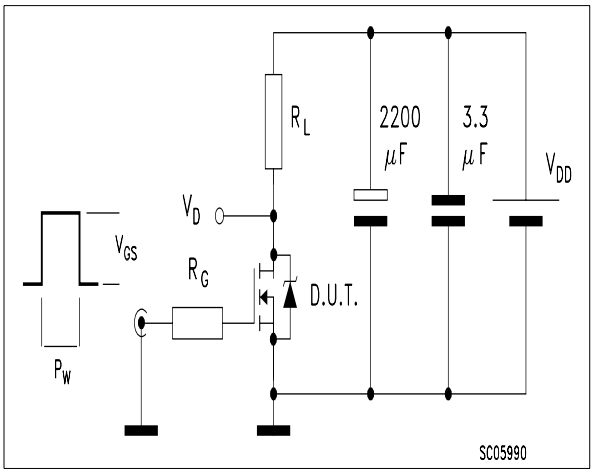



**Fig. 4:** Gate Charge test Circuit

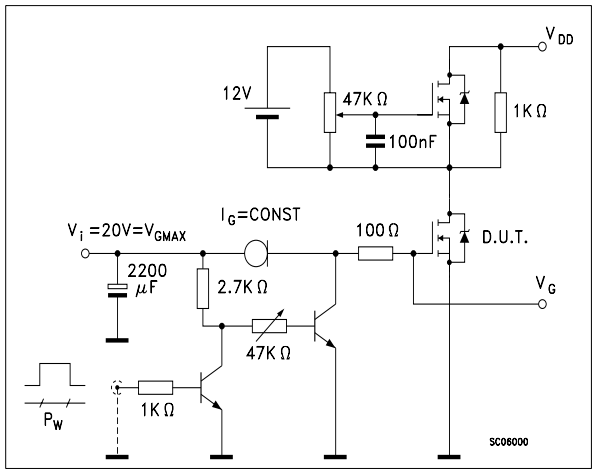
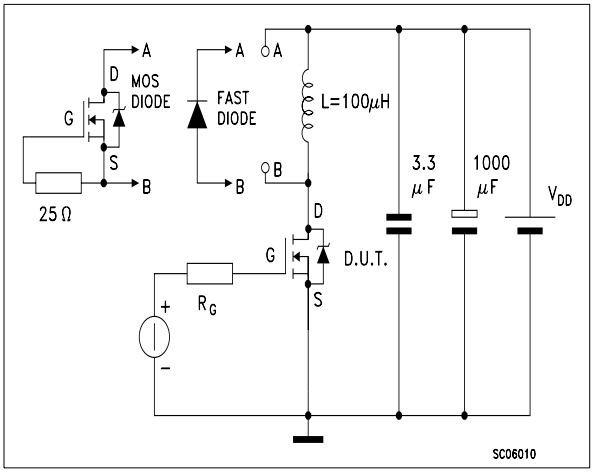
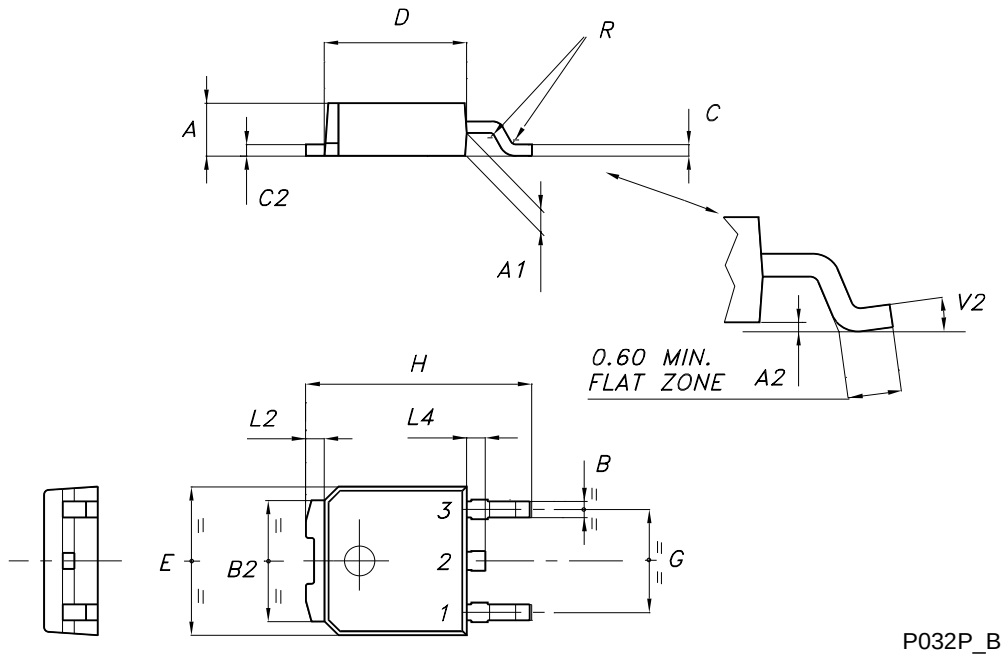



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



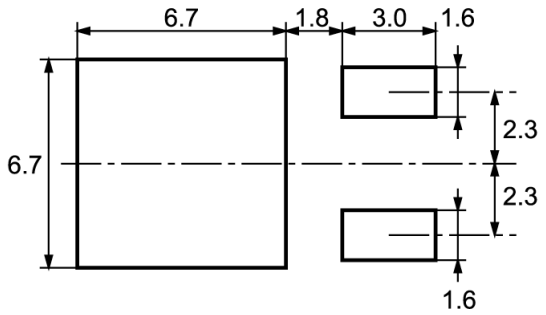
## TO-252 (DPAK) MECHANICAL DATA

| DIM. | mm | | | inch | | |
|---|---|---|---|---|---|---|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.20 | | 2.40 | 0.087 | | 0.094 |
| A1 | 0.90 | | 1.10 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.90 | 0.025 | | 0.035 |
| B2 | 5.20 | | 5.40 | 0.204 | | 0.213 |
| C | 0.45 | | 0.60 | 0.018 | | 0.024 |
| C2 | 0.48 | | 0.60 | 0.019 | | 0.024 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.60 | 0.252 | | 0.260 |
| G | 4.40 | | 4.60 | 0.173 | | 0.181 |
| H | 9.35 | | 10.10 | 0.368 | | 0.398 |
| L2 | | 0.8 | | | 0.031 | |
| L4 | 0.60 | | 1.00 | 0.024 | | 0.039 |
| V2 | $0^o$ | | $8^o$ | $0^o$ | | $0^o$ |



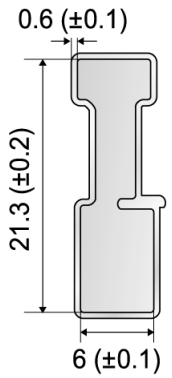

P032P_B

## DPAK FOOTPRINT




All dimensions are in millimeters

## TUBE SHIPMENT (no suffix)*



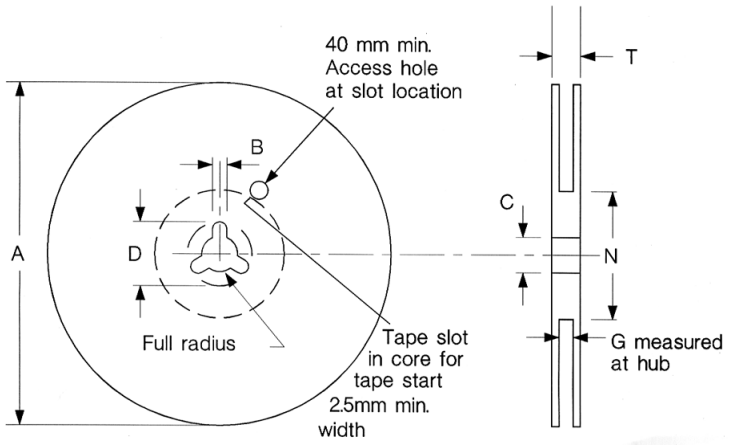

| BASE QTY |
|---|
| 75 |

| BULK QTY |
|---|
| 3000 |

Tube length 532 (±0.5)

All dimensions are in millimeters

## TAPE AND REEL SHIPMENT (suffix "T4")*



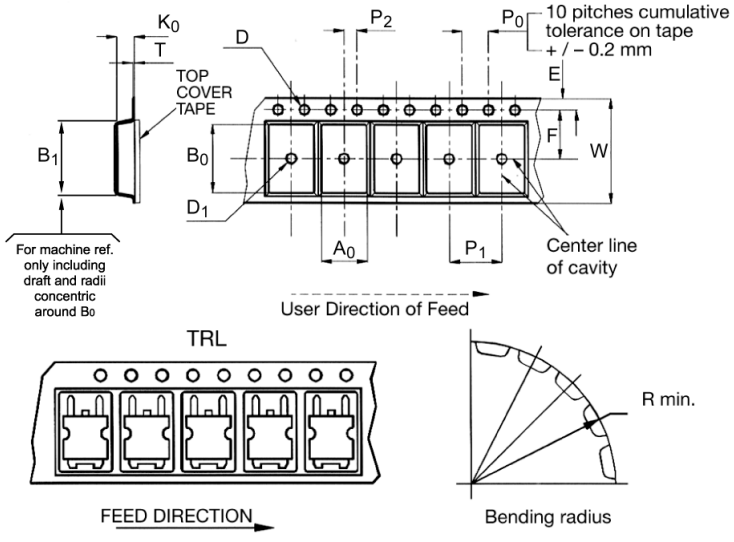

REEL MECHANICAL DATA

| DIM. | mm | | inch | |
|---|---|---|---|---|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 16.4 | 18.4 | 0.645 | 0.724 |
| N | 50 | | 1.968 | |
| T | | 22.4 | | 0.881 |

| BASE QTY | BULK QTY |
|---|---|
| 2500 | 2500 |

TAPE MECHANICAL DATA

| DIM. | mm | | inch | |
|---|---|---|---|---|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 6.8 | 7 | 0.267 | 0.275 |
| B0 | 10.4 | 10.6 | 0.409 | 0.417 |
| B1 | | 12.1 | | 0.476 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.5 | | 0.059 | |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 7.4 | 7.6 | 0.291 | 0.299 |
| K0 | 2.55 | 2.75 | 0.100 | 0.108 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 7.9 | 8.1 | 0.311 | 0.319 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 40 | | 1.574 | |
| W | 15.7 | 16.3 | 0.618 | 0.641 |




* on sales type